

#### **Features**

- Small double-end package
- Viewing Angle = ±37.5°
- High reliability
- Ultra bright red
- RoHS compliance

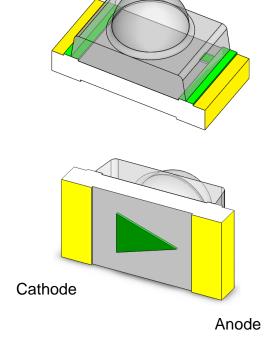
### **Applications**

Red sensor

### **Description**

The RP1608X09-H5 is an AllnGaP Red LED housed in a miniature SMD package. The device has a peak wavelength of 630nm LED spectrally matched with phototransistor or photodiode.

### **Package Outline**



### **Schematic**



## Absolute Maximum Rating at 25°C

Symbol	Parameters	Ratings	Units	Notes
l <sub>F</sub>	Continuous Forward Current	50	mA	
I <sub>FP</sub>	Peak Forward Current	0.5	Α	1
VR	Reverse Voltage	5	V	
T <sub>opr</sub>	Operating Temperature	-40 ~ +85	°С	
T <sub>stg</sub>	Storage Temperature	-40 ~ +100	°C	
T <sub>sol</sub>	Soldering Temperature	260	°C	2
PD	Power Dissipation at(or below) 25°C Free Air Temperature	140	mW	

### Electro-Optical Characteristics TA = 25°C (unless otherwise specified)

### **Optical Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
lv	Luminous Intensity	I <sub>F</sub> =20mA	1155	-	2145	mcd	3
le	Radiant Intensity	I <sub>F</sub> =20mA	-	8.2	-	mW/sr	
λр	Peak Wavelength	I <sub>F</sub> =20mA	-	630	-	nm	
λd	Dominant Wavelength	I <sub>F</sub> =20mA	620	-	625	nm	4
Δλ	Spectral Bandwidth	I <sub>F</sub> =20mA	-	20	-	nm	
θ1/2	Angle of Half Intensity	I <sub>F</sub> =20mA	-	±37.5	-	deg	

#### **Electrical Characteristics**

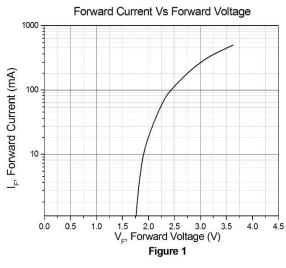
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
V <sub>F</sub> Forward Voltage		I <sub>F</sub> =20mA	1.6	2.0	2.4	\/	
		I <sub>F</sub> =50mA	1.9	2.3	2.8	V	
I <sub>R</sub>	Reverse Current	V <sub>R</sub> =5V	-	-	10	μA	

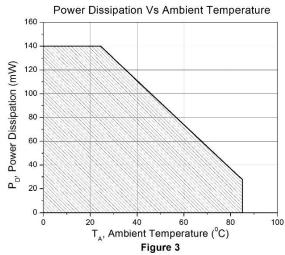
#### Notes:

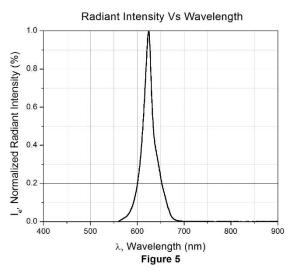
- 1. I<sub>FP</sub> Conditions--Pulse Width $\leq$  100 $\mu$ s and Duty $\leq$  10%.
- 2. Soldering time ≤ 5 seconds.
- 3. Tolerance of Luminous Intensity:  $\pm 10\%$ .
- 4. Tolerance of Dominant Wavelength: ±2nm.

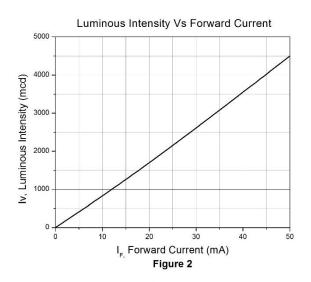


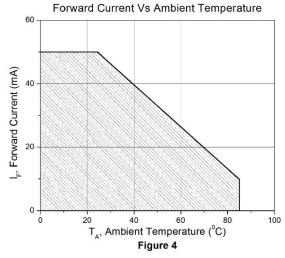
## **Typical Characteristic Curves**



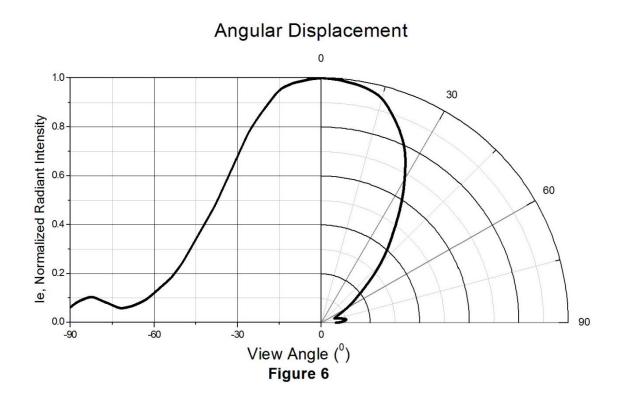






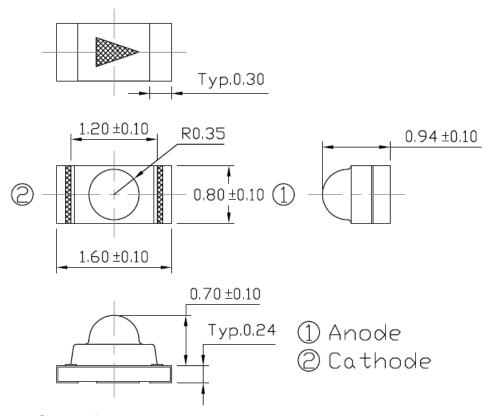


## **Typical Characteristic Curves**

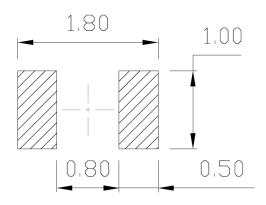




## Package Dimension All dimensions are in mm, unless otherwise stated



### Recommended Soldering Mask All dimensions are in mm, unless otherwise stated

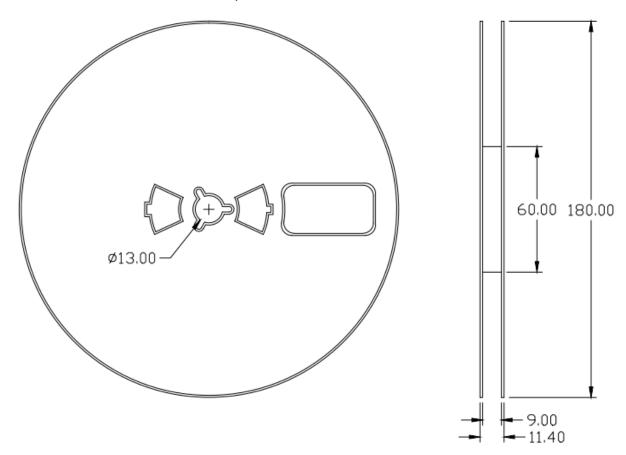


## **Ordering Information**

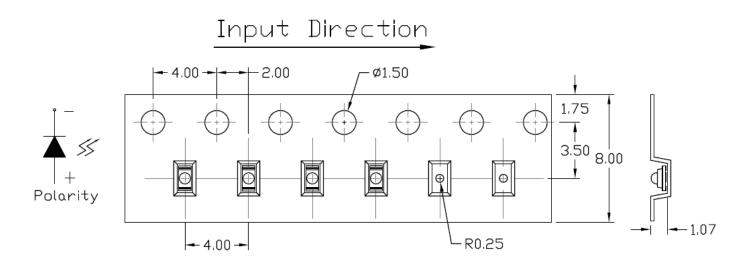
Part Number	Description	Quantity
RP1608X09-H5	Tape & Reel	4000 pcs



### Reel Dimension All dimensions are in mm, unless otherwise stated



Tape Dimension All dimensions are in mm, unless otherwise stated





### **Label Form Specification**



Part no: CTM Production Number

Serial no: Production Number

Lot no: Lot number

Q'ty: Packing Quantity

Date Code: Manufacture Date

Bin Code: Iv Ranks

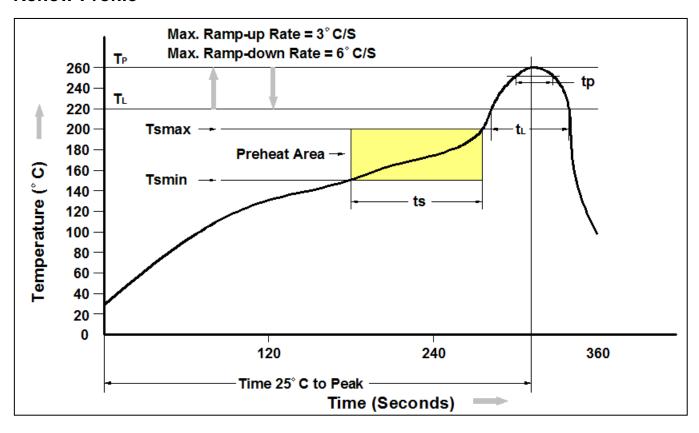
MADE IN CHINA: Production Place

#### **Storage Condition**

- 1. Do not open moisture proof bag before the products are ready to use.
- 2. The moisture barrier bag should be stored at 30°C and 90%R.H. max. before opening. Shelf life of non-opened bag is 12 months after the bag sealing date.
- 3. After opening the moisture barrier bag floor life is 168h at 30°C/60%RH. max. Unused LEDs should be resealed into moisture barrier bag. (Refer to J-STD-020 Standard)
- 4. If the moisture absorbent material has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the J-STD-033 Standard conditions.



### **Reflow Profile**



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t⊳)	3°C/second max.
Liquidous Temperature (T <sub>L</sub> )	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t <sub>P</sub> ) within 5°C of 260°C	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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- A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.